

AUTOMATIC MODE SHIFT / 150mA LOW VOLTAGE REGULATOR

EA-175-071023

OUTLINE

R1118 Series are CMOS-based voltage regulator ICs with ultra low supply current (Typ.5.5 μ A), and remarkable improved transient response compared with the conventional low supply current voltage regulator. The supply current of these ICs is automatically shifts between fast mode and low power mode, it depending on the load current. (The current threshold is fixed internally). These ICs are capable of the low input voltage (Min.1.4V) and the output voltage range from 0.8V is possible. The output voltage of R1118 is fixed in the IC.

Each of these ICs consists of a voltage reference unit, an error amplifier, a resistor net for setting output voltage, a current limit circuits for over-current.

A standby mode with ultra low supply current can be realized with the chip enable function.

Since the packages for these ICs are SOT-23-5 and DFN(PLP)1612-4B (H: 0.4mm), therefore high density mounting of the ICs on boards is possible.

FEATURES

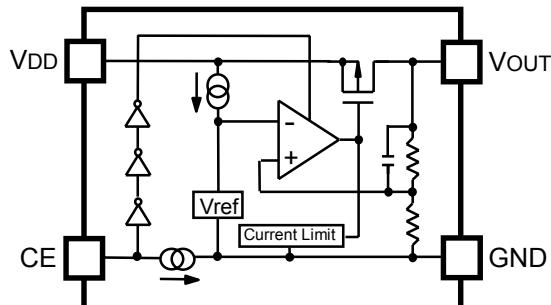
- Supply Current (Low power Mode) TYP. 5.5 μ A ($I_{OUT}=0mA$)
- Supply Current (Fast Mode) TYP. 50 μ A ($I_{OUT}=11mA$)
- Supply Current (Standby Mode) TYP. 0.1 μ A
- Input Voltage Range 1.4V ~ 6.0V
- Output Voltage Range 0.8V ~ 4.2V
- Dropout Voltage TYP. 0.27V ($I_{OUT}=150mA$, $V_{OUT}=2.8V$)
- Output Voltage Accuracy $\pm 1.0\%$ ($1.5V < V_{OUT} \leq 3.5V$)
- Ripple Rejection TYP. 70dB ($f=1kHz$)
..... TYP. 60dB ($f=10kHz$)
- Excellent Line Regulation TYP. 0.02%/V
- Packages DFN(PLP)1612-4B (H=0.4mm), SOT-23-5
- Built-in Short Current Limit Circuit TYP. 40mA
- Ceramic capacitors are recommended to be used this IC $C_{IN}=C_{OUT}=1.0\mu F$

APPLICATIONS

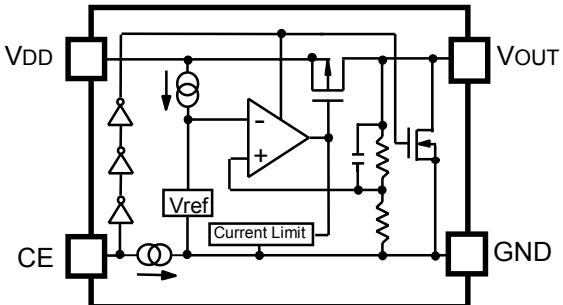
- Power source for portable communication equipment.
- Power source for electrical appliances such as cameras, VCRs and camcorders.
- Power source for battery-powered equipment.
- Power source for home appliances

BLOCK DIAGRAM

R1118xxx1B



R1118xxx1D



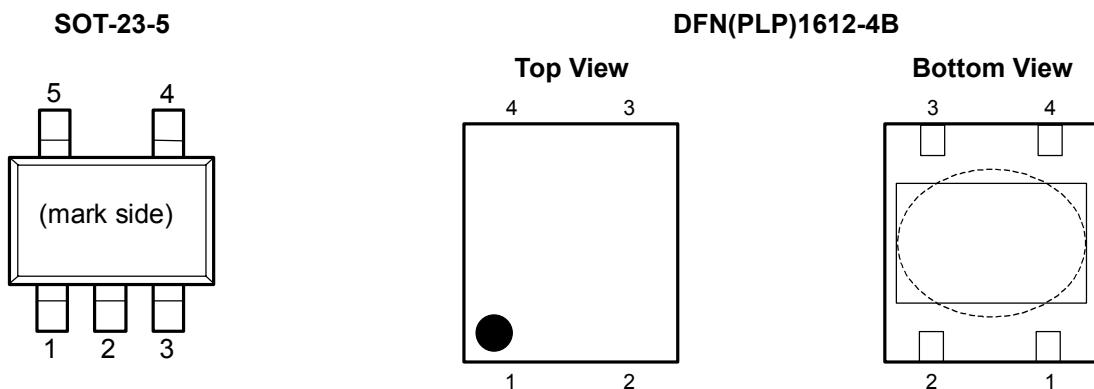
SELECTION GUIDE

The output voltage, version, and the taping type for the ICs can be selected at the user's request. The selection can be made with designating the part number as shown below;

R1118xxxx-XX ←Part Number
 ↑↑↑↑
 a b c d

Code	Contents
a	Designation of Package Type: N: SOT-23-5 K: DFN(PLP)1612-4B (H: 0.4mm)
b	Setting Output Voltage (V_{OUT}) : Fixed Type: 08 to 42 Stepwise setting with 0.1V increment in the range from 0.8V to 4.2V Exception: 1.85V=R1118x181x5-xx :2.85V=R1118x281x5-xx
c	Designation of Active Type: B: active high type D: active high type, with auto-discharge
d	Designation of Taping Type: Ex.TR (refer to Taping Specifications: TR type is the standard direction)

PIN CONFIGURATION



PIN DESCRIPTIONS

R1118N : SOT-23-5

Pin No.	Symbol	Description
1	V_{DD}	Input Pin
2	GND	Ground Pin
3	CE	Chip Enable Pin ("H" Active)
4	NC	No Connection
5	V_{OUT}	Output Pin

R1118K : DFN(PLP)1612-4B

Pin No.	Symbol	Description
1	V_{OUT}	Output Pin
2	GND	Ground Pin
3	CE	Chip Enable Pin ("H" Active)
4	V_{DD}	Input Pin

Tab is GND level.(They are connected to the reverse side of this IC)

Do not connect to other wires or land patterns.

ABSOLUTE MAXIMUM RATINGS

Symbol	Item	Rating		Unit
V_{IN}	Input Voltage	6.5		V
V_{CE}	Input Voltage (CE pin)	- 0.3 ~ 6.5		V
V_{OUT}	Output Voltage	- 0.3 ~ V_{IN} +0.3		V
I_{OUT}	Output Current	180		mA
P_D	Power Dissipation*	SOT-23-5	420	mW
		DFN(PLP)1612-4B	580	
T_a	Ambience Temperature Range	- 40°C ~ +85°C		°C
Tstg	Storage Temperature Range	- 55°C ~ +125°C		°C

* For Power Dissipation, please refer to the PACKAGE INFORMATION.

ELECTRICAL CHARACTERISTICS

V_{IN} = Set V_{OUT} + 1V, I_{OUT} =1mA, unless otherwise noted.

values indicate -40°C ≤ T_a ≤ 85°C, unless otherwise noted.

(T_a =25°C)

Symbol	Item	Conditions	MIN.	TYP.	MAX.	Unit
V_{OUT}	Output Voltage	$V_{OUT} \leq 1.5V$	-15mV -40mV		15mV 30mV	V
		$1.5V < V_{OUT} \leq 3.5V$	$V_{OUT} \times 0.99$ $V_{OUT} \times 0.973$		$V_{OUT} \times 1.01$ $V_{OUT} \times 1.02$	
		$3.5V < V_{OUT}$	$V_{OUT} \times 0.985$ $V_{OUT} \times 0.968$		$V_{OUT} \times 1.015$ $V_{OUT} \times 1.025$	
I_{OUT}	Output Current		150			mA
$\Delta V_{OUT} / \Delta I_{OUT}$	Load Regulation	$1mA \leq I_{OUT} \leq 150mA$			80	mV
V_{DIF}	Dropout Voltage	Refer to the Dropout Voltage Specifications table				
I_{SS1}	Supply Current (Low Power Mode)	$I_{OUT}=0mA$		5.5	16	μA
I_{SS2}	Supply Current (Fast Mode)	$I_{OUT}=11mA$		50	105	μA
$I_{STANDBY}$	Supply Current (Standby)	$V_{IN}=6.0V, V_{CE}=GND$		0.1	1.0	μA
I_{OUTH}	Fast Mode Current Threshold	$I_{OUT}=1\mu A \rightarrow 30mA$		7	12	mA
I_{OUTL}	Low Power Mode Current Threshold	$I_{OUT}=30mA \rightarrow 1\mu A$	1	2		mA
$\Delta V_{OUT} / \Delta V_{IN}$	Line Regulation	$V_{OUT}+0.5V \leq V_{IN} \leq 6.0V$ (Incase that $V_{OUT} \leq 0.9V$ $1.4V \leq V_{IN}$)		±0.02	±0.2	%/V
RR	Ripple Rejection	$f=1kHz$ $f=10kHz$ Ripple 0.2Vp-p, $I_{OUT}=30mA$ (Incase that $V_{OUT}<1.5V$)		70 60		dB

		$V_{IN} = \text{Set } V_{OUT} + 1.5V$)				
V_{IN}	Input Voltage		[1.4]		[6.0]	V
$\Delta V_{OUT}/\Delta T$	Output Voltage Temperature Coefficient	$-40^{\circ}\text{C} \leq Ta \leq 85^{\circ}\text{C}$		± 100		ppm/ $^{\circ}\text{C}$
I_{LIM}	Short Current	$V_{OUT}=0V$		40		mA
I_{PD}	CE Pull-down Constant Current		[0.01]	0.30	[0.6]	μA
V_{CEH}	CE Input Voltage "H"		[1.0]			V
V_{CEL}	CE Input Voltage "L"				[0.4]	V
en	Output Noise	BW10Hz ~ 100kHz		100		μVRms
R_{LOW}	Nch On Resistance for Auto Discharge (D version Only)	$V_{CE}=0V$		40		Ω

The specifications in are guaranteed by design.

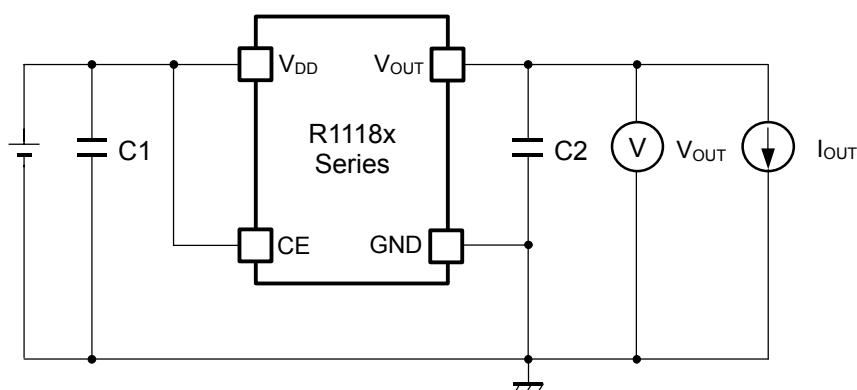
All specifications are specified under load conditions such that $T_j \approx Ta=25^{\circ}\text{C}$ except for items of Output Noise, Ripple Rejection and Output Voltage Temperature Coefficient.

Dropout Voltage

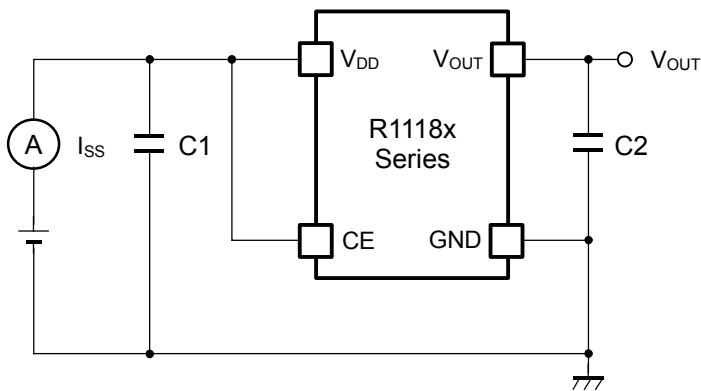
V_{OUT} (V)	Dropout Voltage (V)		
	Condition	TYP.	MAX.
$0.8 \leq V_{OUT} < 0.9$	$I_{OUT}=150\text{mA}$	0.82	[1.06]
$0.9 \leq V_{OUT} < 1.0$		0.74	[0.98]
$1.0 \leq V_{OUT} < 1.2$		0.66	[0.90]
$1.2 \leq V_{OUT} < 1.5$		0.54	[0.77]
$1.5 \leq V_{OUT} < 2.0$		0.45	[0.64]
$2.0 \leq V_{OUT} < 2.8$		0.34	[0.49]
$2.8 \leq V_{OUT}$		0.27	[0.37]

The values in are guaranteed by design.

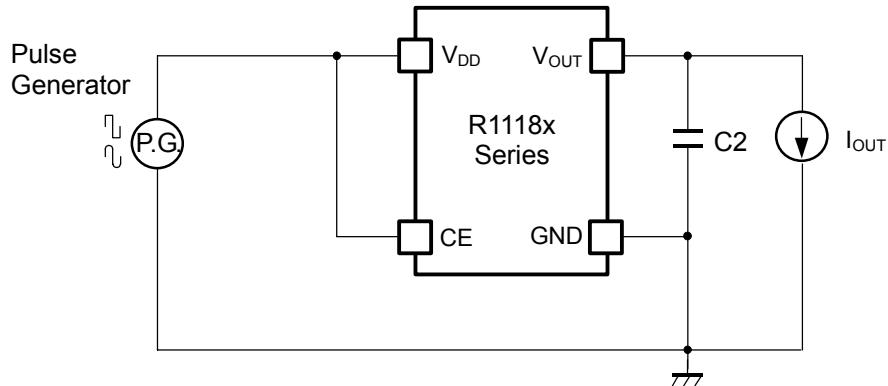
TEST CIRCUITS



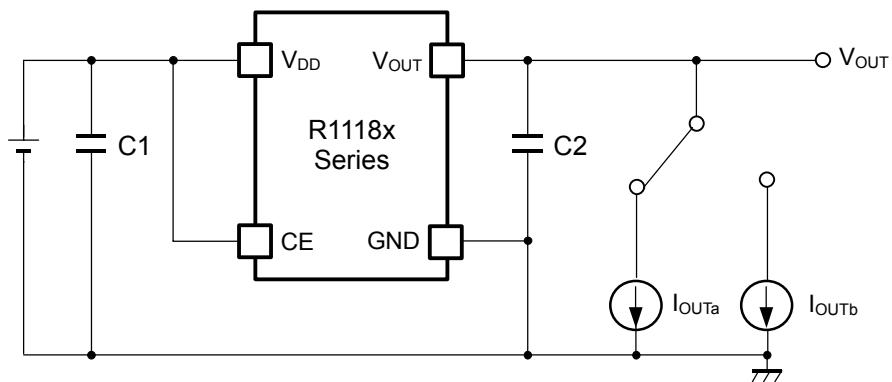
Standard Test Circuit



Test Circuit for Supply Current



Test Circuit for Ripple Rejection



Test Circuit for Load Transient Response

TECHNICAL NOTES

When using these ICs, consider the following points:

Phase Compensation

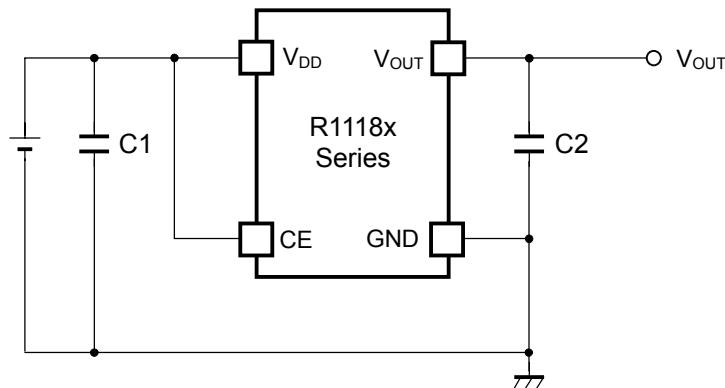
In these ICs, phase compensation is made for securing stable operation even if the load current is varied. For this purpose, use a capacitor C_{OUT} with good frequency characteristics and ESR (Equivalent Series Resistance). (Note: If additional ceramic capacitors are connected with parallel to the output pin with an output capacitor for phase compensation, the operation might be unstable. Because of this, test these ICs with as same external components as ones to be used on the PCB.)

PCB Layout

Make V_{DD} and GND lines sufficient. If their impedance is high, noise pickup or unstable operation may result. Connect a capacitor with a capacitance value as much as $1.0\mu F$ or more between V_{DD} and GND pin, and as close as possible to the pins.

Set external components, especially the output capacitor, as close as possible to the ICs, and make wiring as short as possible

TYPICAL APPLICATION

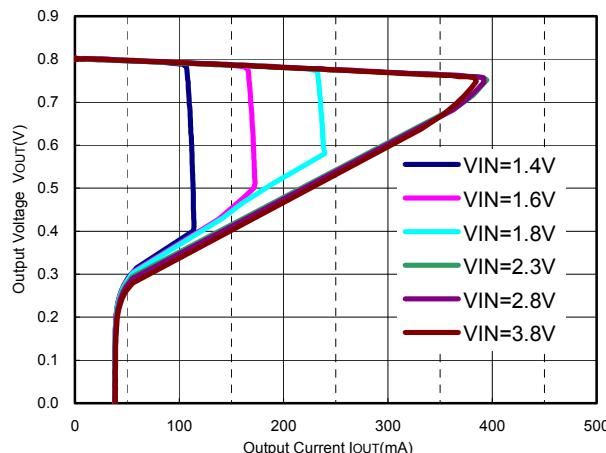


(External Components)

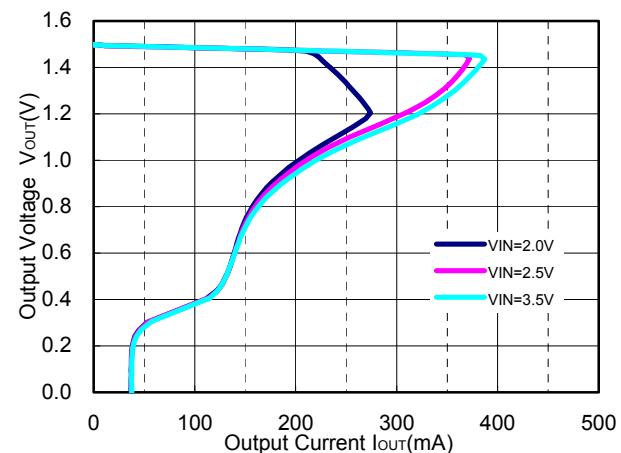
Output Capacitor	1.0 μF	TDK C1005JB0J105K
	Kyocera CM05X5R105K06AB	

TYPICAL CHARACTERISTICS

1) Output Voltage vs. Output Current ($T_{opt}=25^{\circ}C$)
R1118X081X

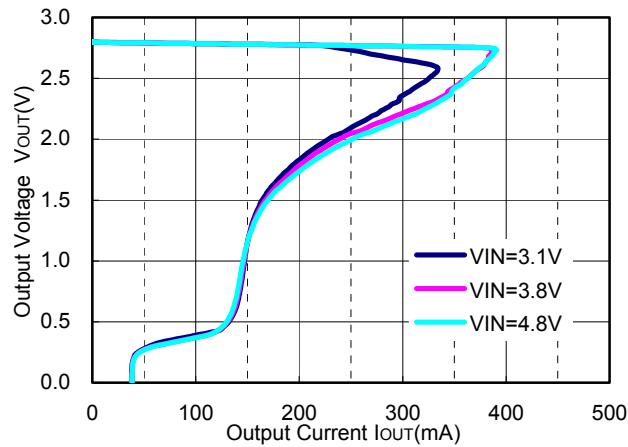


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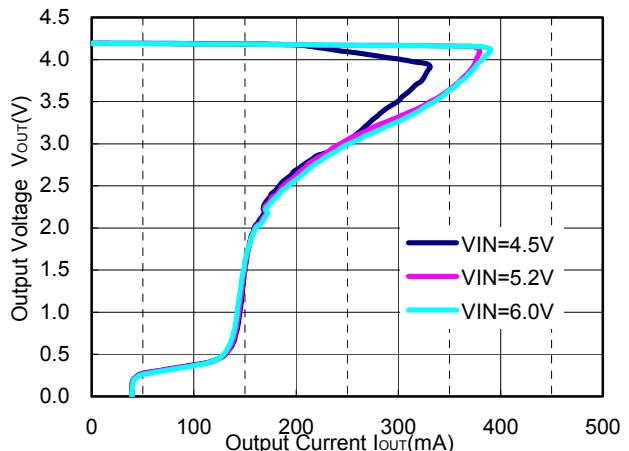


R1118

R1118X281X

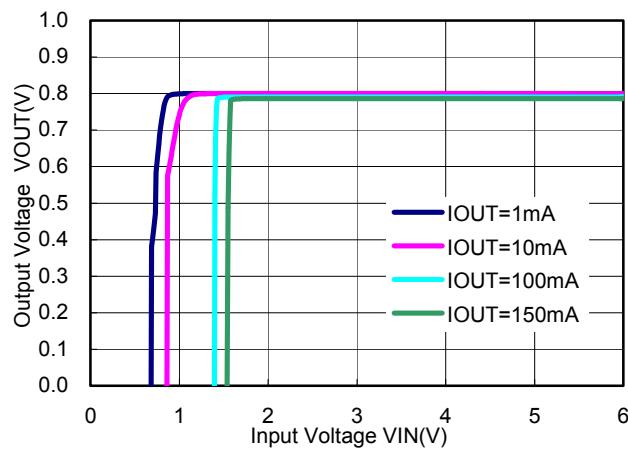


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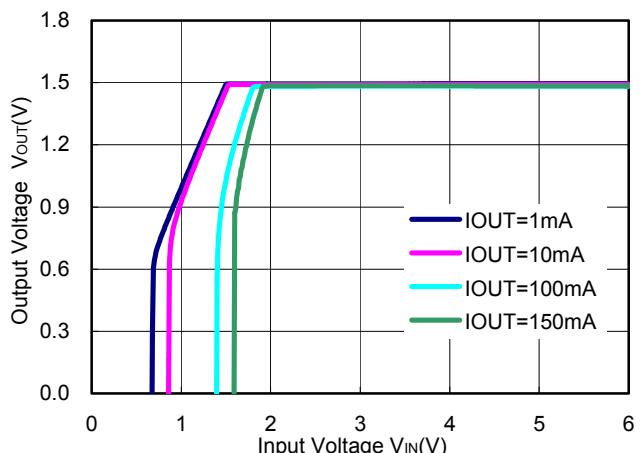


2) Input Voltage vs. Output Voltage (Topt=25°C)

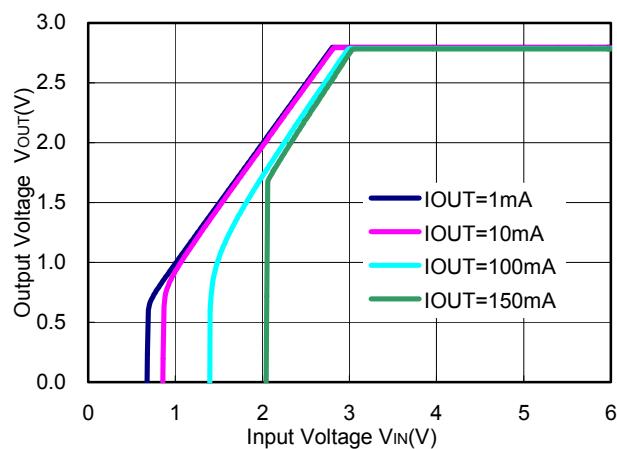
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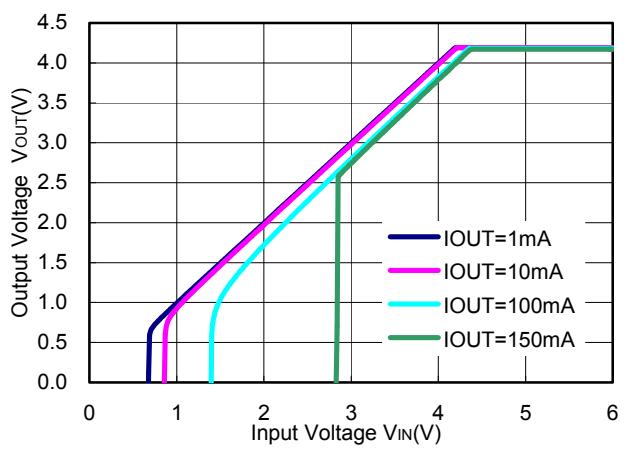
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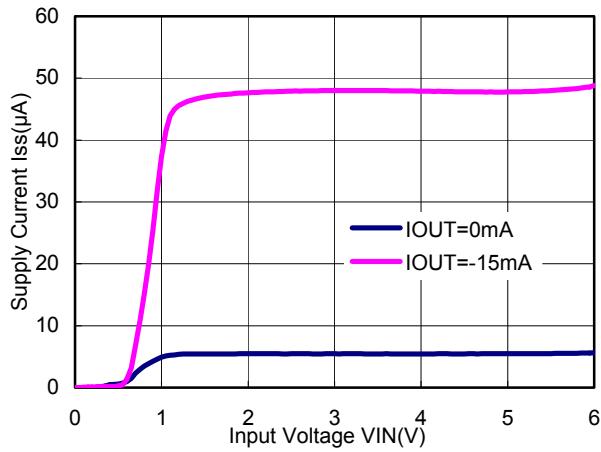
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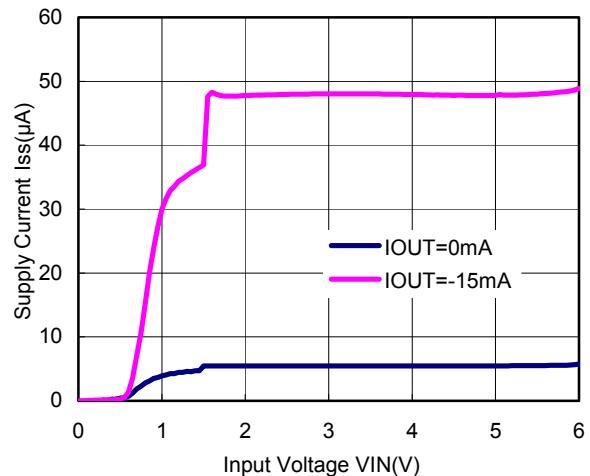
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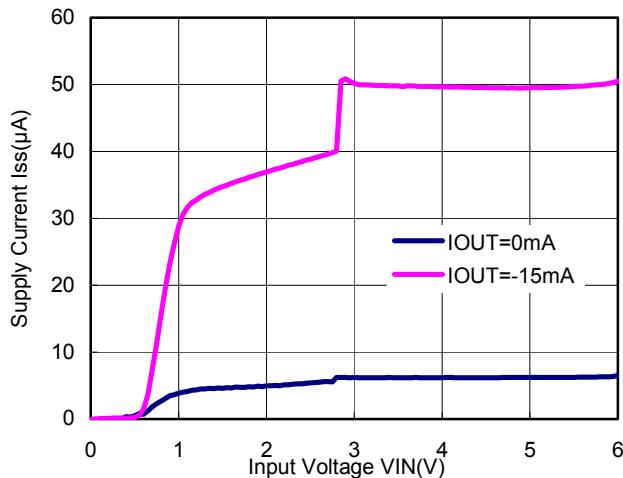
3) Supply Current vs. Input Voltage ($T_{opt}=25^{\circ}\text{C}$)
R1118X081X



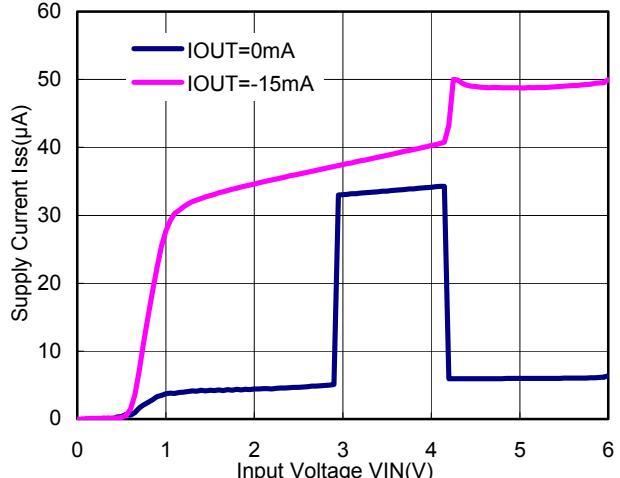
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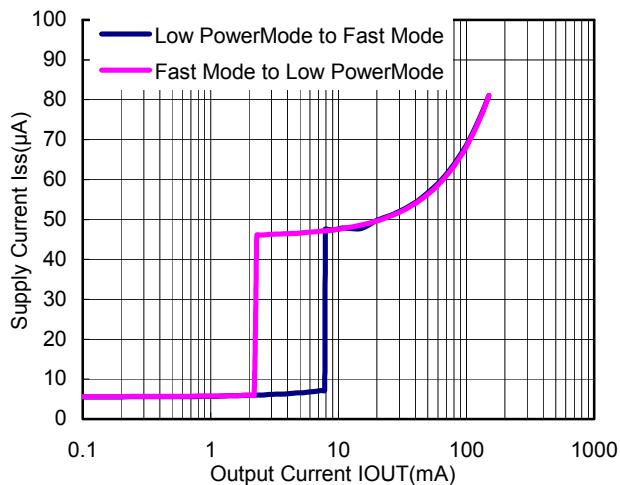
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R1118X421X



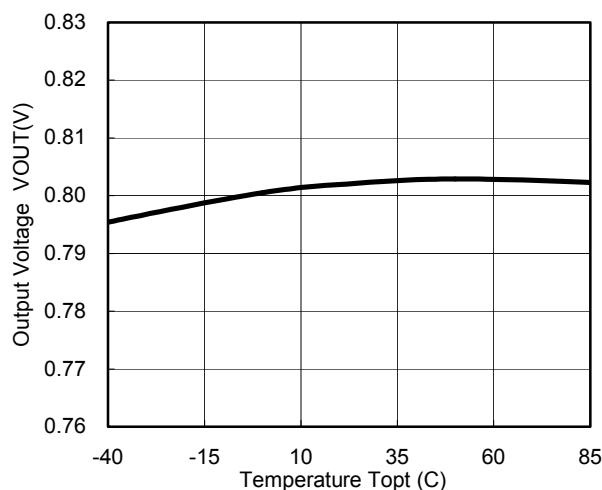
4) Supply Current vs. Output Current ($T_{opt}=25^{\circ}\text{C}$)
R1118X



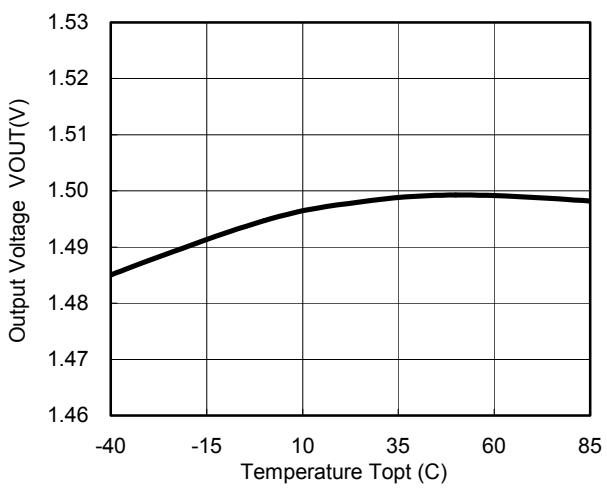
R1118

5) Output Voltage vs. Temperature

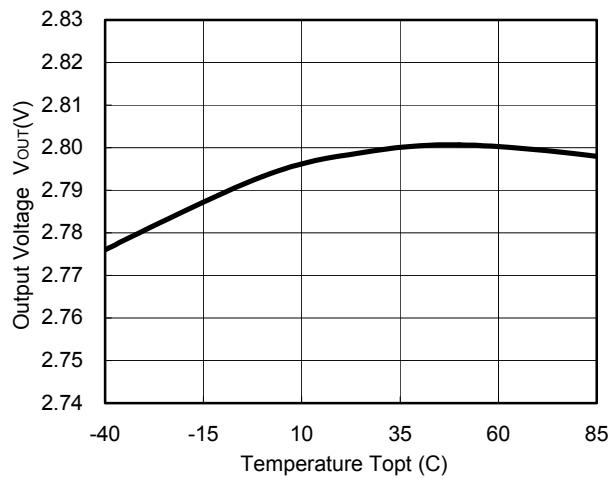
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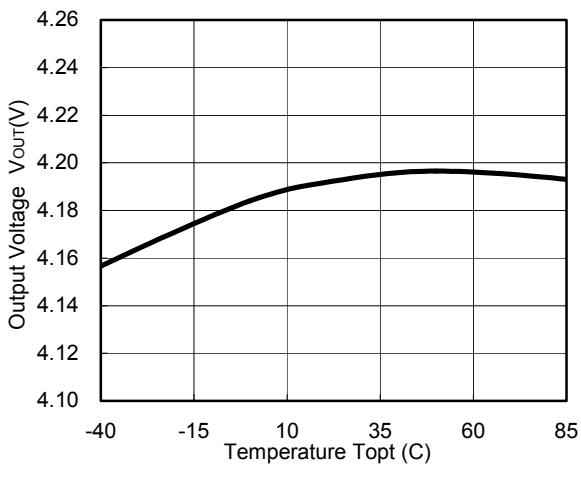
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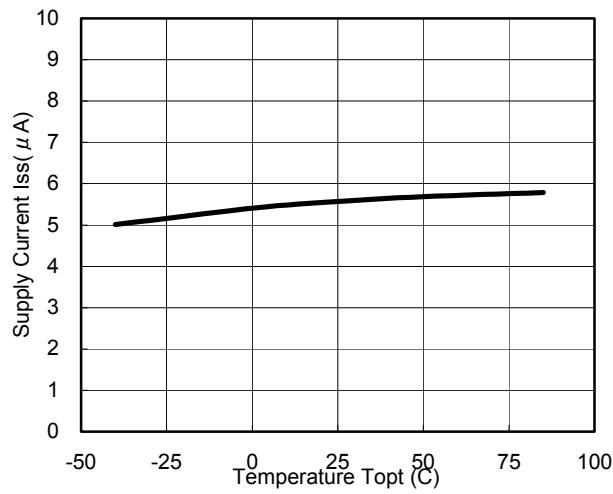


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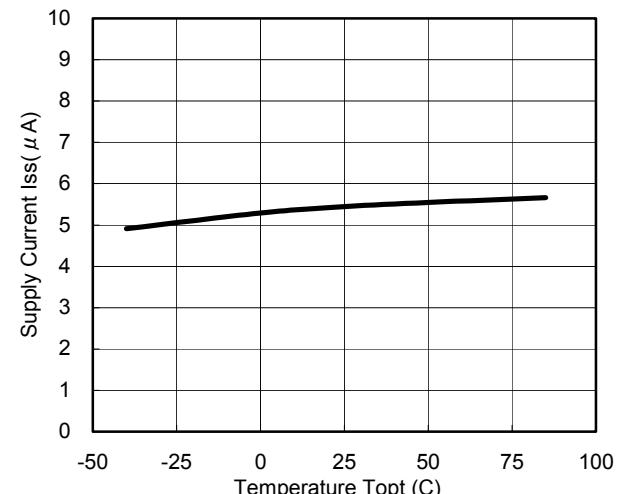


6) Supply Current vs. Temperature

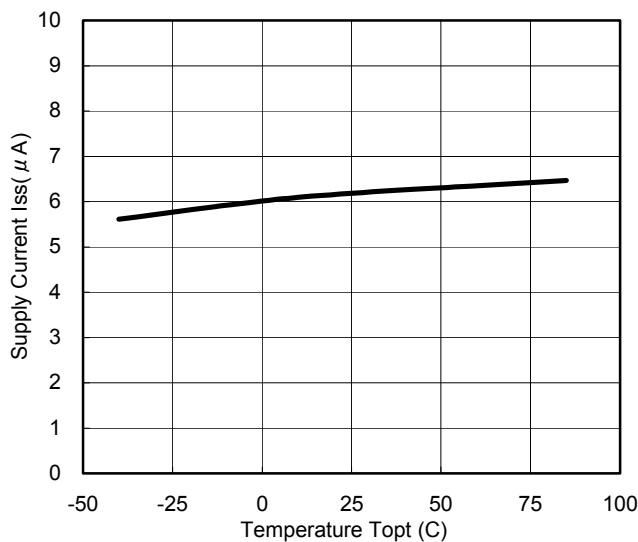
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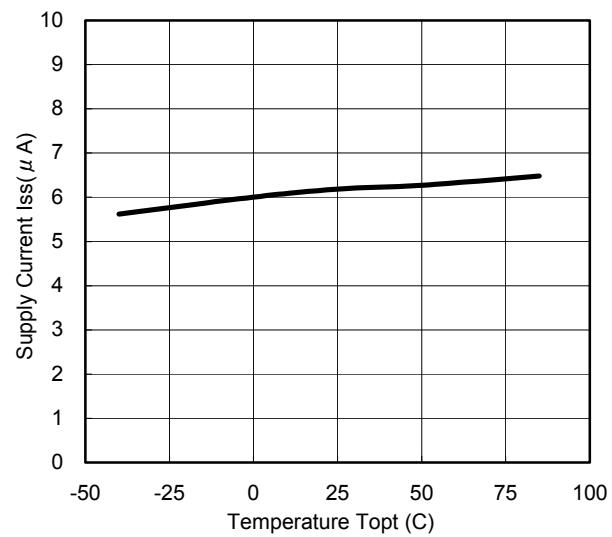
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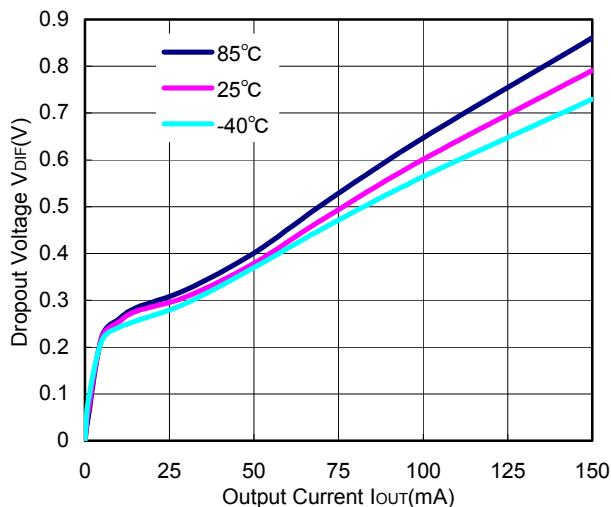


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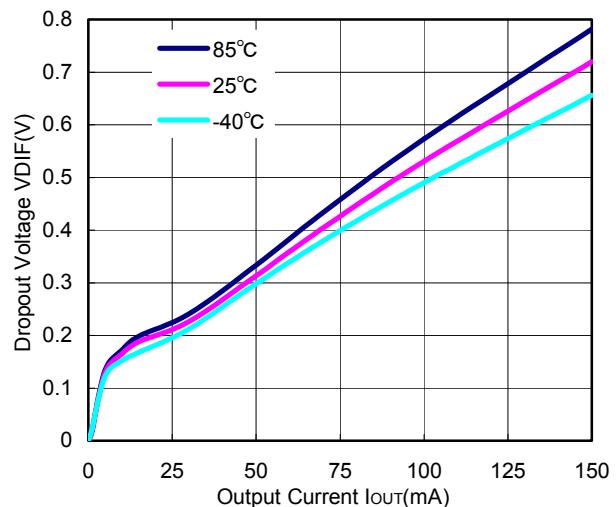


7) Dropout Voltage vs. Output Current

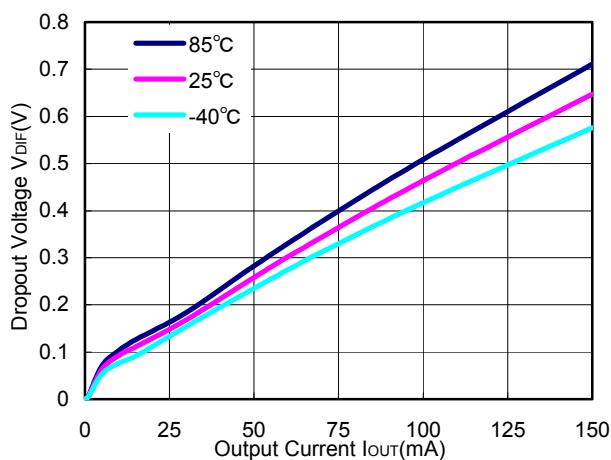
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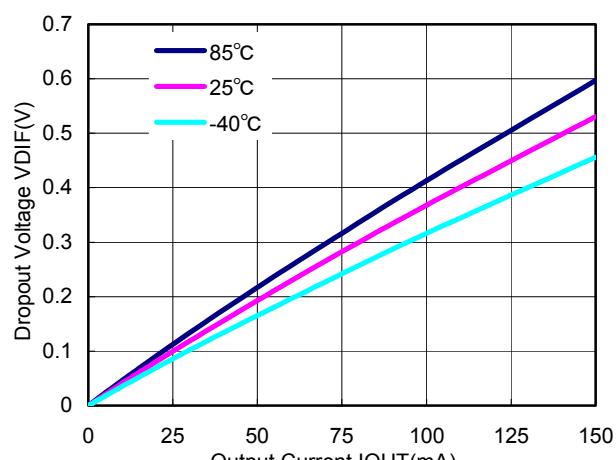
R1118X091X



R1118X101X

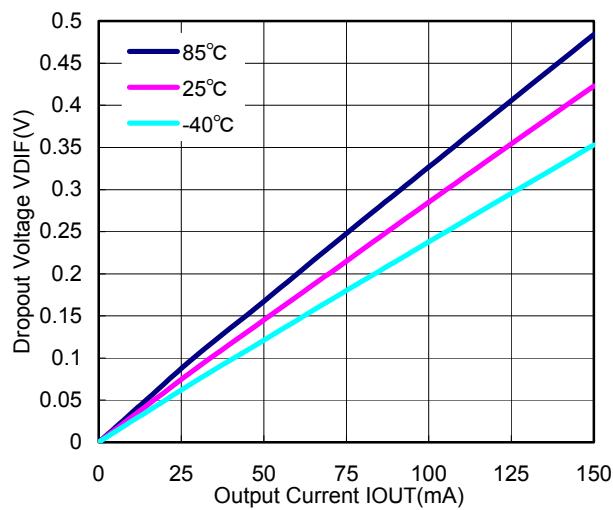


R1118X121X

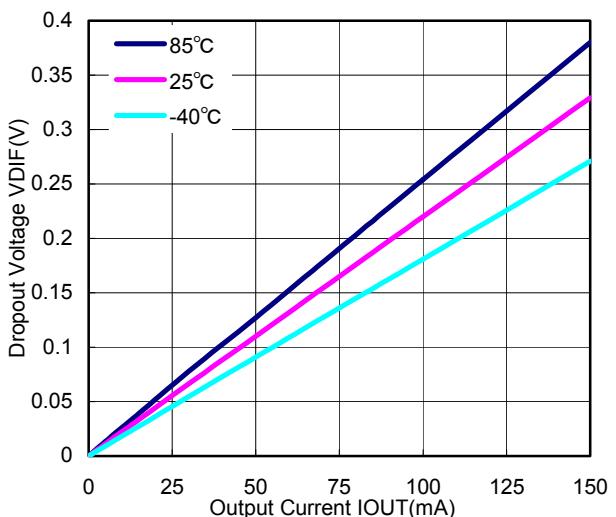


R1118

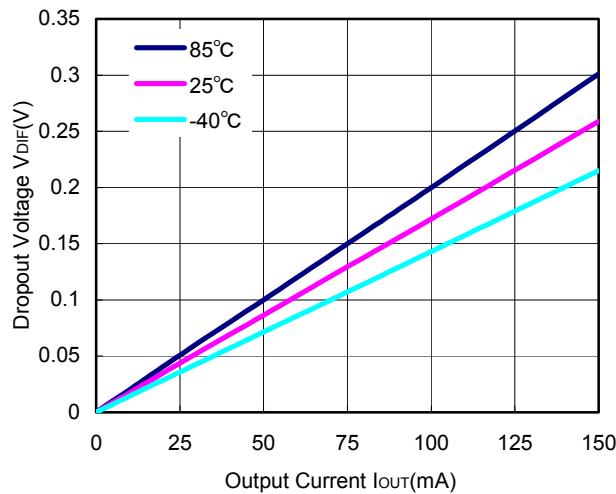
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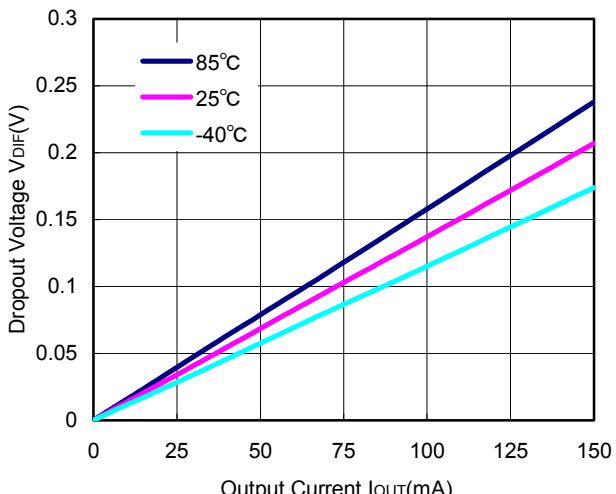
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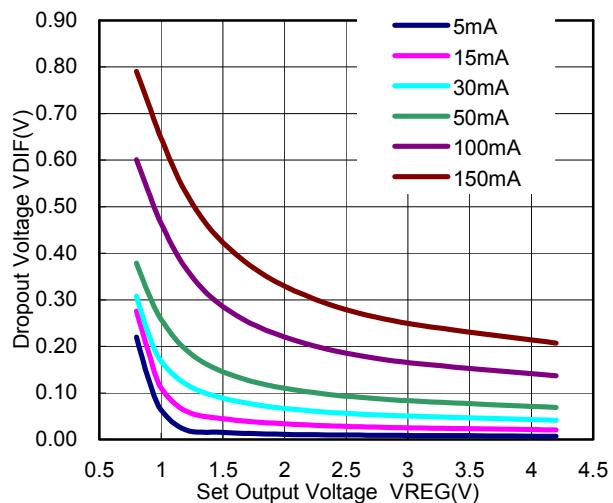
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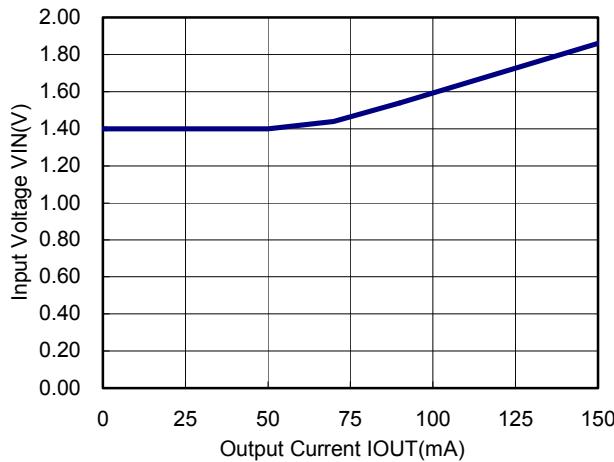
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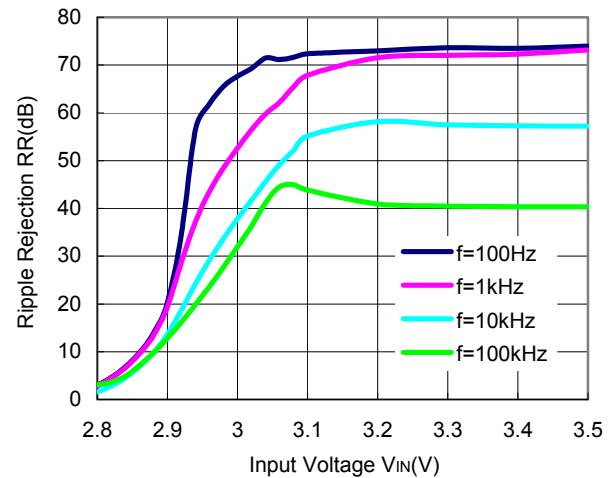
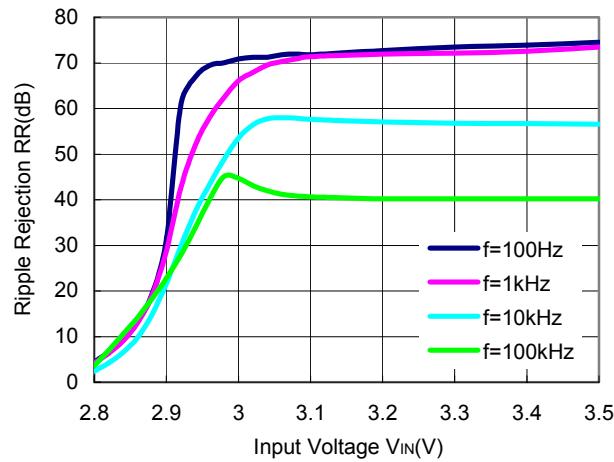
8) Dropout Voltage vs. Set Output Voltage ($T_{opt}=25^{\circ}\text{C}$)



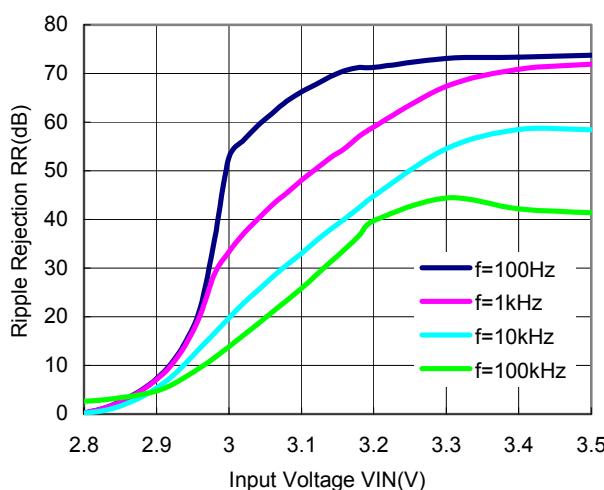
9) Minimum Operating Voltage
R1118X081X



10) Ripple Rejection vs. Input Voltage(T_{opt}=25°C), Ripple=0.2Vp-p,C_{IN}=none,C_{OUT}=Ceramic1.0μF, R1118X281X
I_{OUT}=5mA



I_{OUT}=50mA

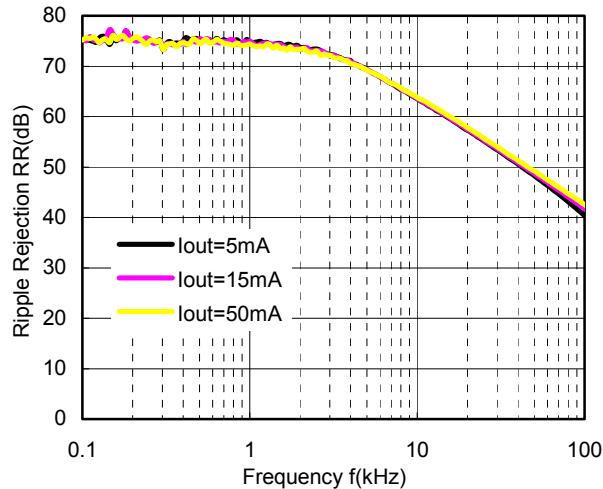


R1118

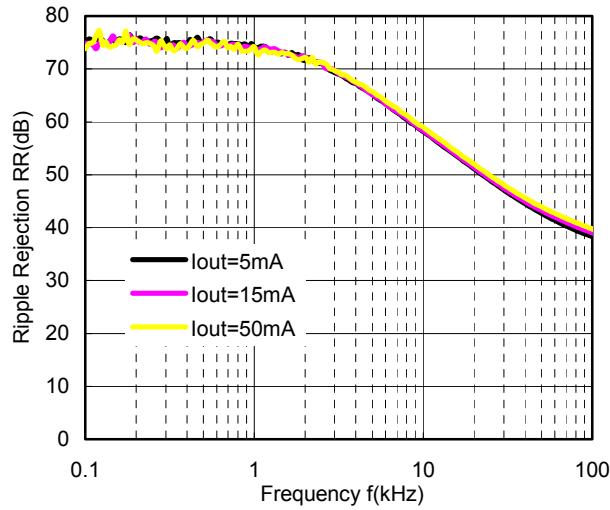
11) Ripple Rejection vs. Frequency ($T_{opt}=25^{\circ}\text{C}$), $C_{IN}=\text{none}$

R1118X081X $V_{IN}=2.3\text{VDC}+0.2\text{Vp-p}$, $C_{out}=1.0\mu\text{F}$

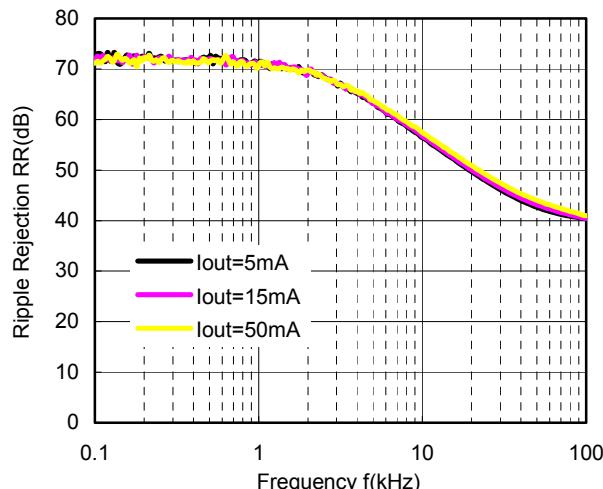
R1118X081X $V_{IN}=2.3\text{VDC}+0.2\text{Vp-p}$, $C_{out}=2.2\mu\text{F}$



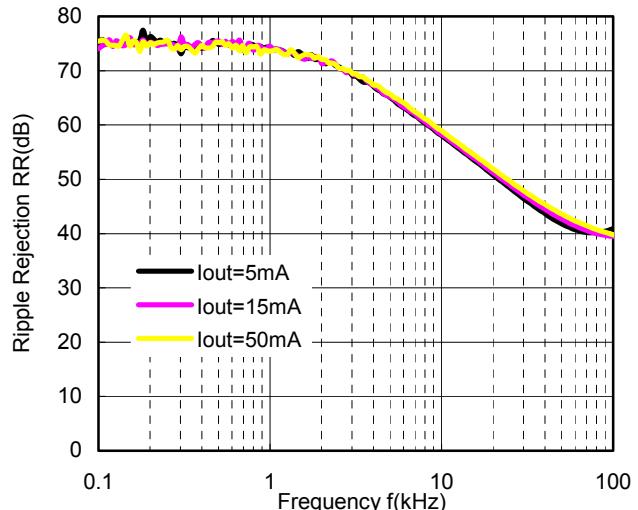
R1118X151X $V_{IN}=2.5\text{VDC}+0.2\text{Vp-p}$, $C_{out}=1.0\mu\text{F}$



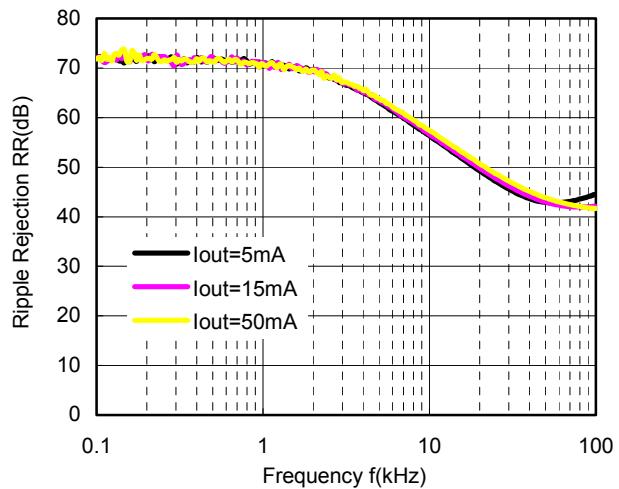
R1118X281X $V_{IN}=3.8\text{VDC}+0.2\text{Vp-p}$, $C_{out}=1.0\mu\text{F}$



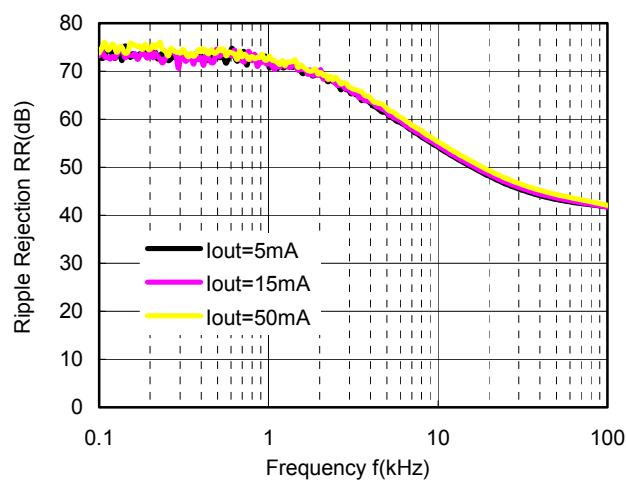
R1118X151X $V_{IN}=2.5\text{VDC}+0.2\text{Vp-p}$, $C_{out}=2.2\mu\text{F}$



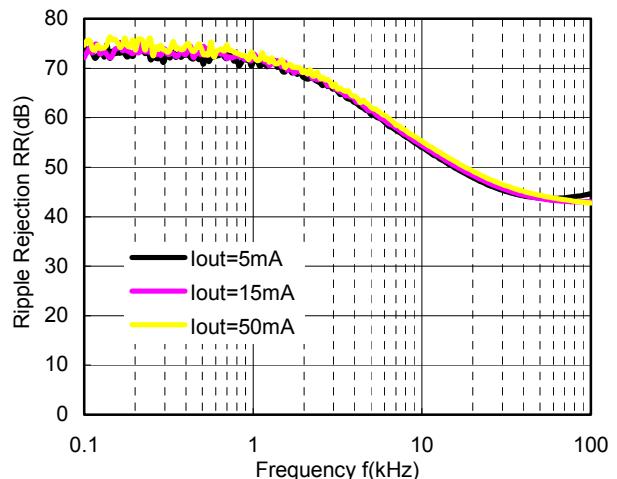
R1118X281X $V_{IN}=3.8\text{VDC}+0.2\text{Vp-p}$, $C_{out}=2.2\mu\text{F}$



R1118X421X VIN=5.2VDC+0.2Vp-p, Cout=1.0uF

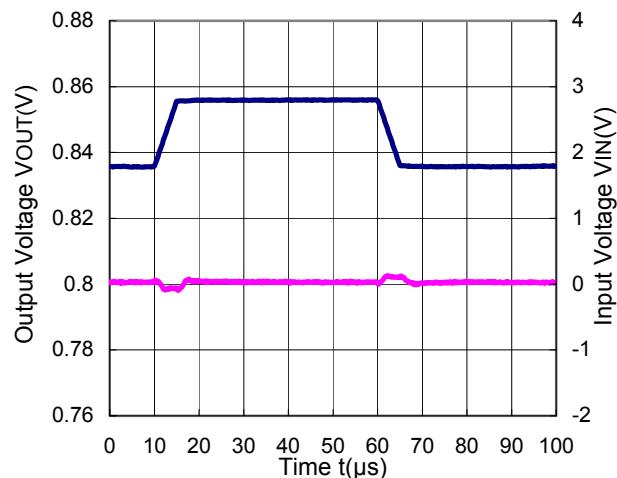


R1118X421X VIN=5.2VDC+0.2Vp-p, Cout=2.2uF

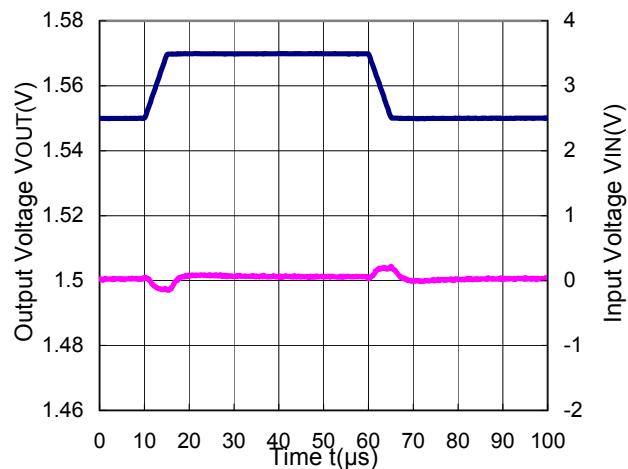


12) Input Transient Response (IOUT=30mA, tr=tf=5μs, CIN=none, COUT=1μF Topt=25°C)

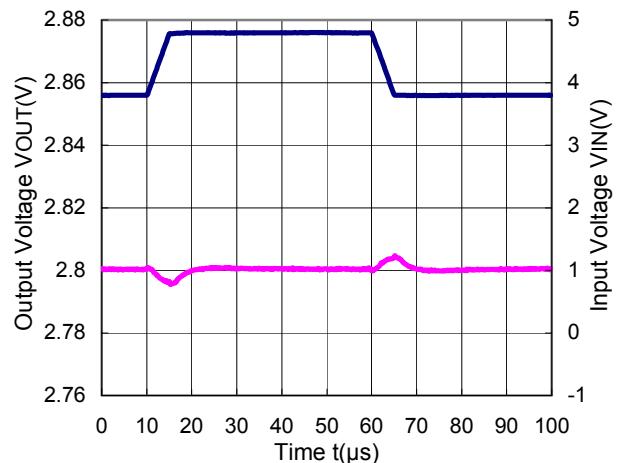
R1118X081X



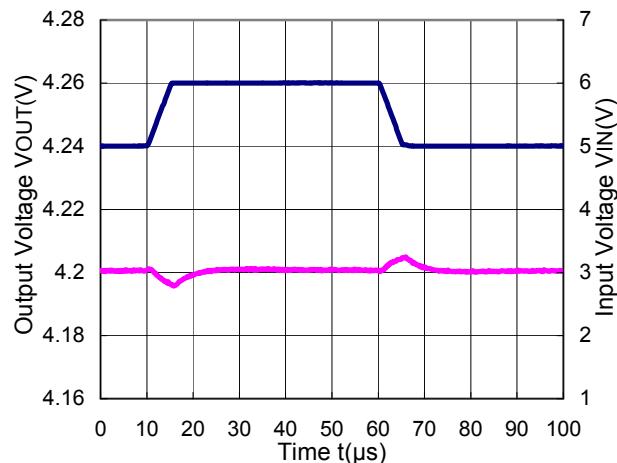
R1118X151X



R1118X281X



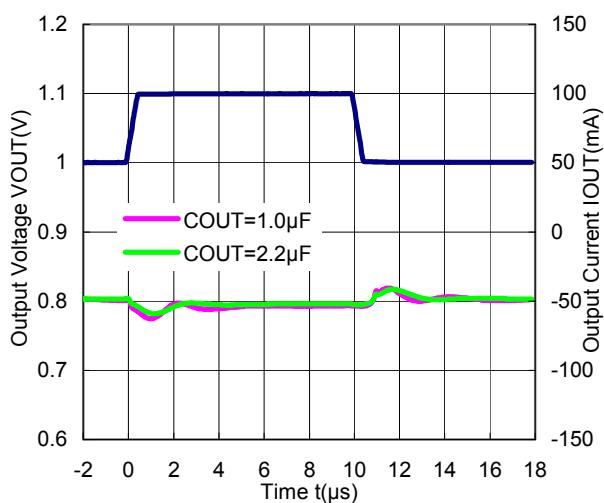
R1118X421X



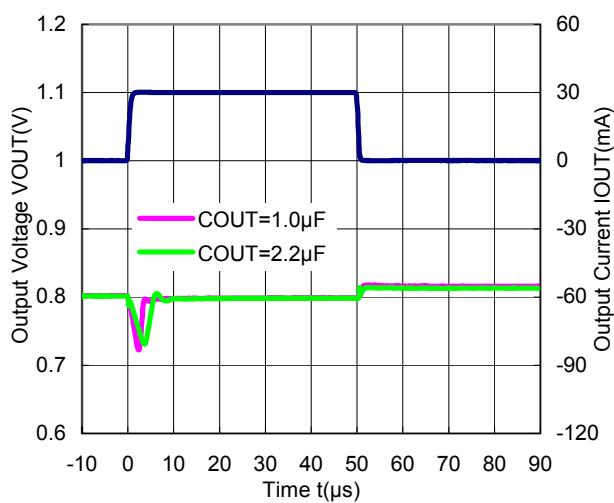
R1118

13) Load Transient Response ($tr=tf=500\text{ns}$, $C_{IN}=\text{Ceramic } 1.0\mu\text{F}$, $T_{opt}=25^\circ\text{C}$)

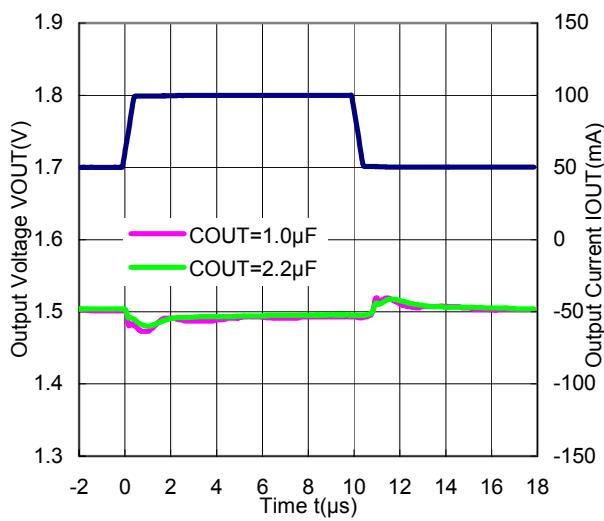
R1118X081X



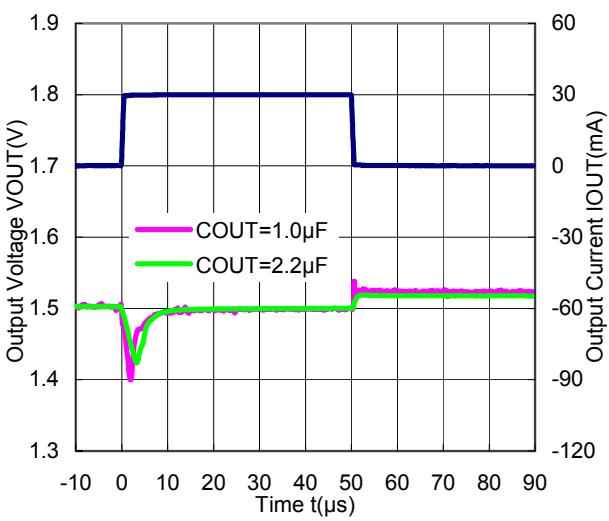
R1118X081X



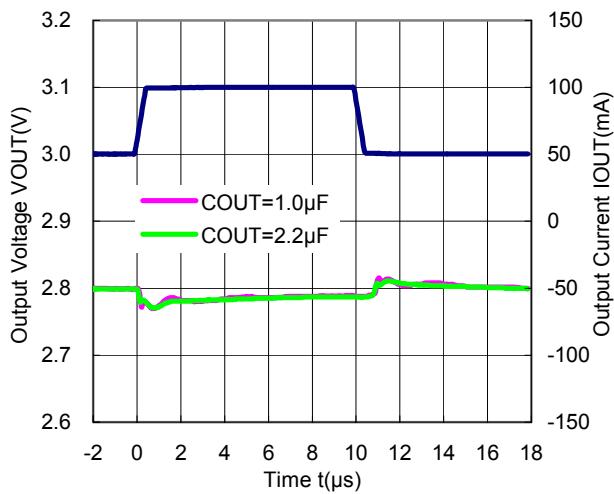
R1118X151X



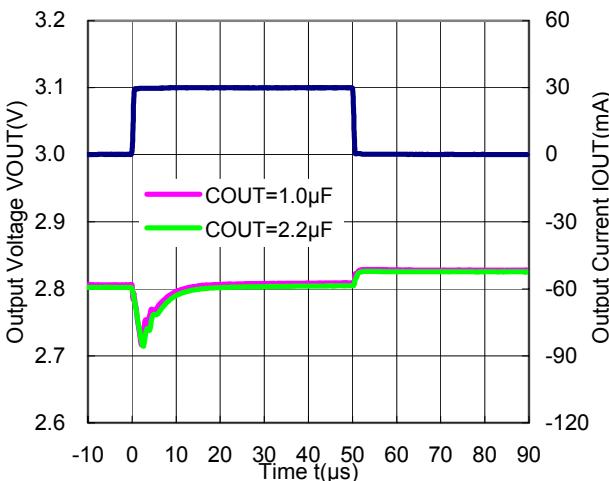
R1118X151X

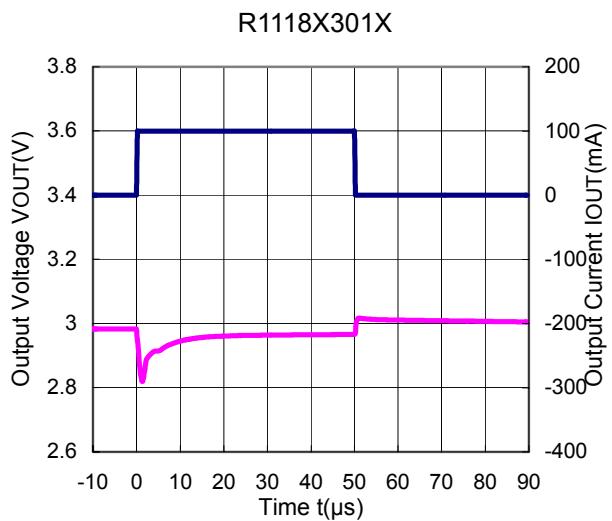
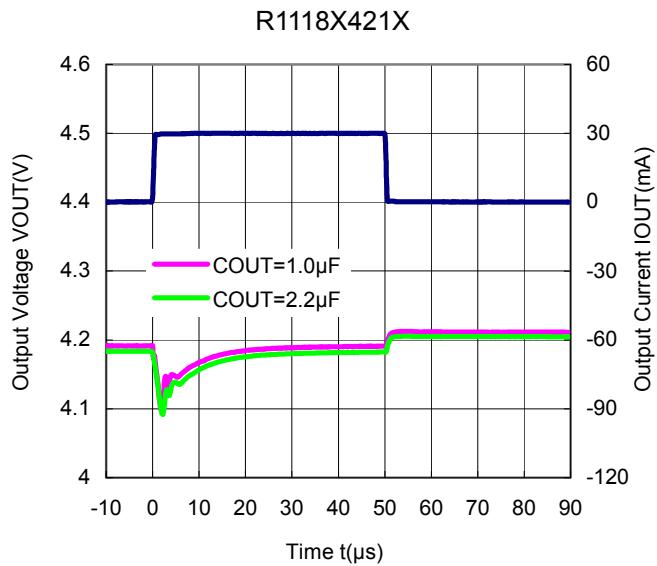
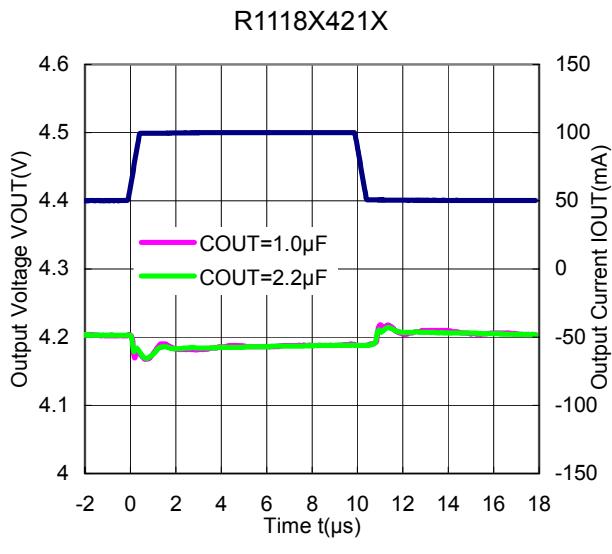


R1118X281X



R1118X281X

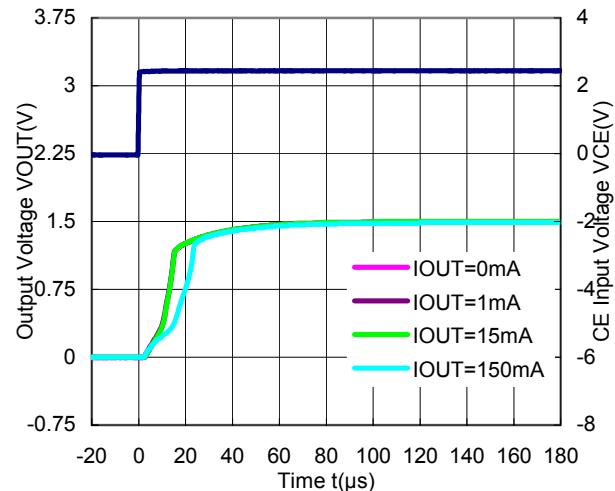
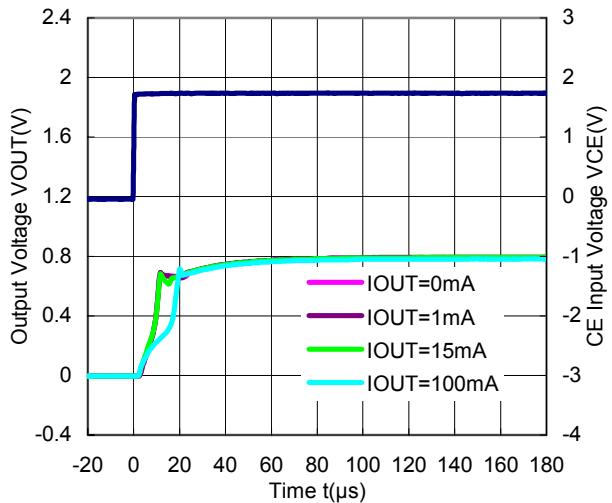




14) Turn-on speed by CE signal (C_{IN} =Ceramic1.0μF, C_{OUT} =Ceramic1.0μF, $T_{opt}=25^{\circ}C$)

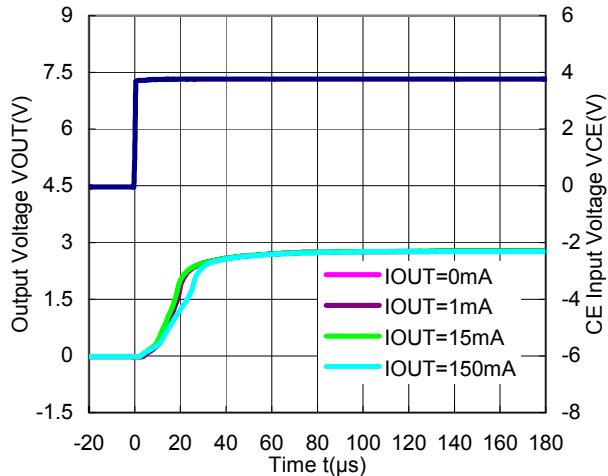
R1118X081X ($V_{IN}=1.8V$)

R1118X151X ($V_{IN}=2.5V$)

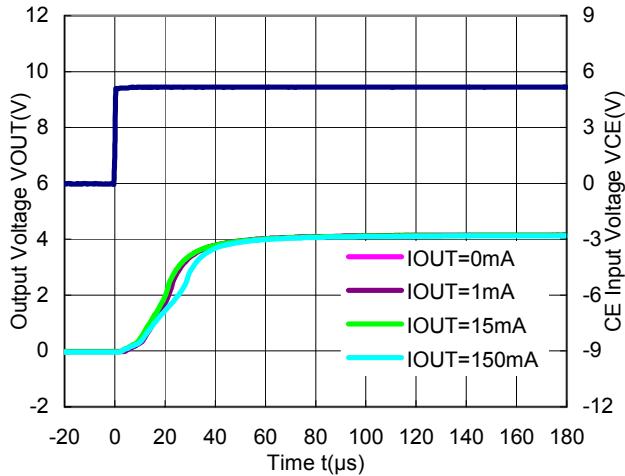


R1118

R1118X281X ($V_{IN}=3.8V$)

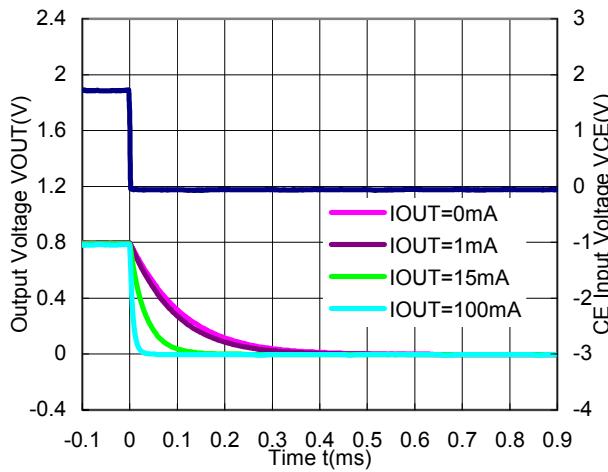


R1118X421X ($V_{IN}=5.2V$)

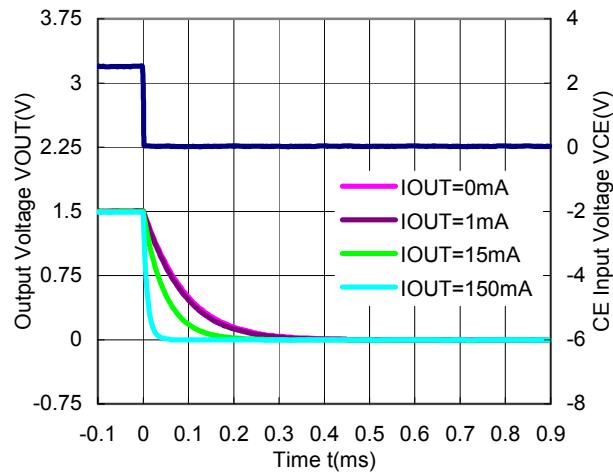


15) Turn-off speed by CE signal (C_{IN} =Ceramic $1.0\mu F$, C_{OUT} =Ceramic $1.0\mu F$, $T_{opt}=25^{\circ}C$)

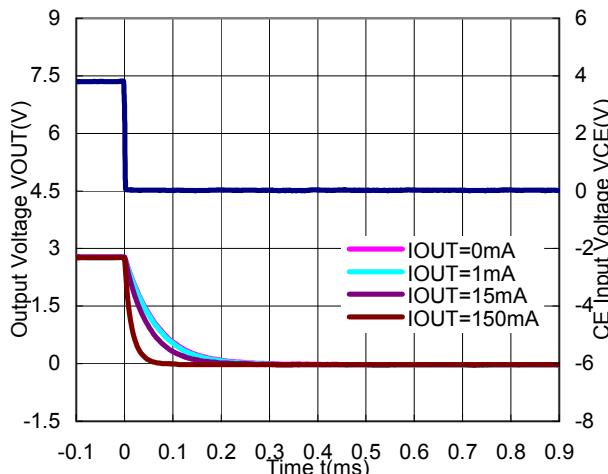
R1118X081X ($V_{IN}=1.8V$)



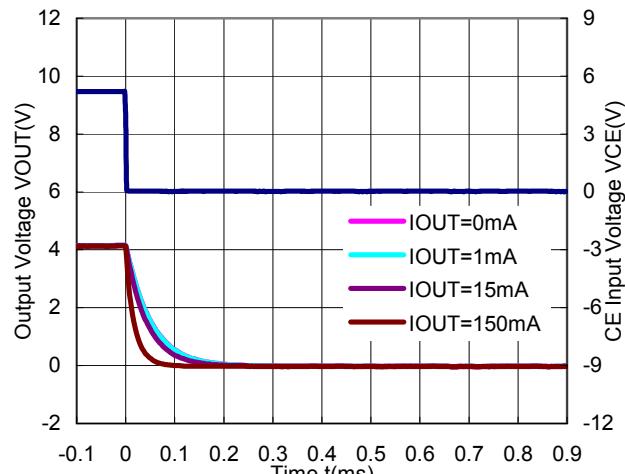
R1118X151X ($V_{IN}=2.5V$)



R1118X281X ($V_{IN}=3.8V$)

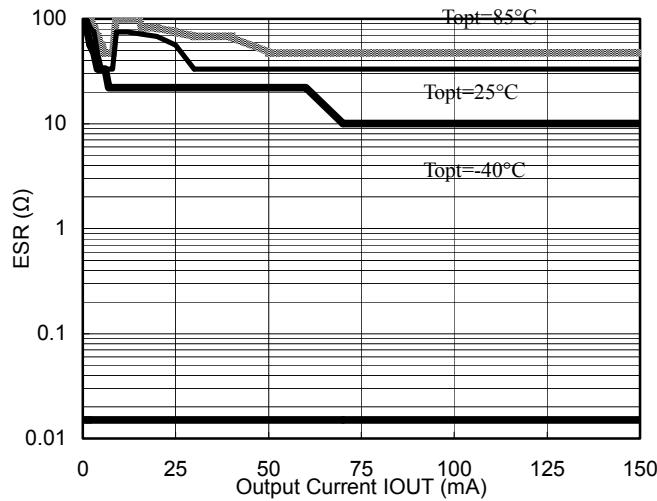


R1118X421X ($V_{IN}=5.2V$)

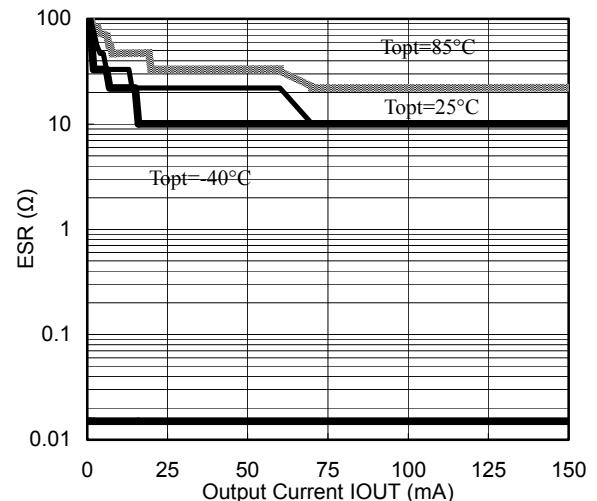


16) Output Capacitor ESR value vs. Output Current (describes the operation stable area border) CIN,
COUT:1.0 μ F (Murata,GRM155B31A105KE)

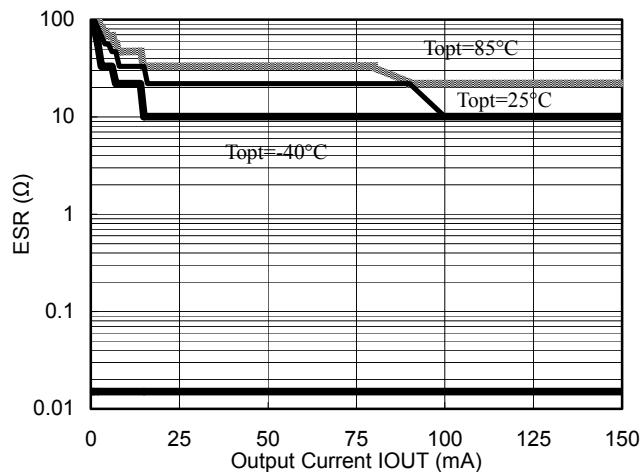
R1118X081X (VIN=1.4V to 6.0V)



R1118X281X (VIN=2.9V to 6.0V)



R1118X421X (VIN=4.3V to 6.0V)



POWER DISSIPATION (SOT-23-5)

This specification is at mounted on board. Power Dissipation (P_D) depends on conditions of mounting on board. This specification is based on the measurement at the condition below:

(Power Dissipation (SOT-23-5) is substitution of SOT-23-6.)

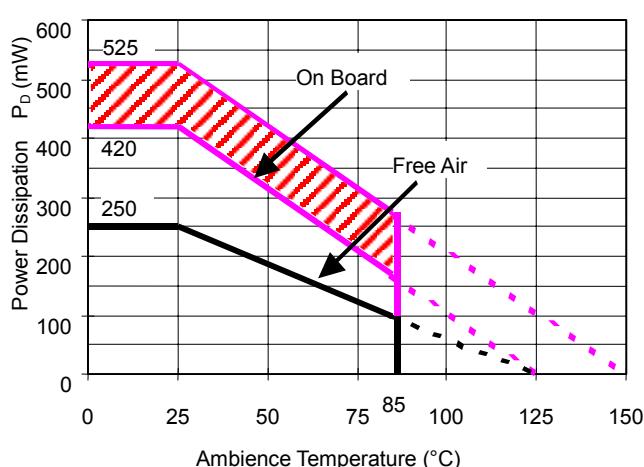
Measurement Conditions

	Standard Test Land Pattern
Environment	Mounting on Board (Wind velocity=0m/s)
Board Material	Glass cloth epoxy plastic (Double sided)
Board Dimensions	40mm*40mm*1.6mm
Copper Ratio	Top side: Approx. 50%, Back side: Approx. 50%
Through-holes	φ 0.5mm * 44pcs

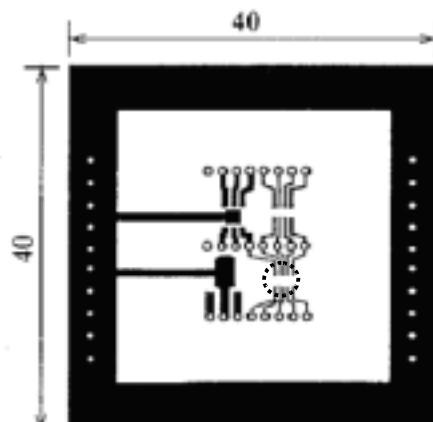
Measurement Result

($T_a=25^{\circ}\text{C}$)

	Standard Test Land Pattern	Free Air
Power Dissipation	420mW($T_{jmax}=125^{\circ}\text{C}$) 525mW($T_{jmax}=150^{\circ}\text{C}$)	250mW($T_{jmax}=125^{\circ}\text{C}$)
Thermal Resistance	$\theta_{ja} = (125-25^{\circ}\text{C})/0.42\text{W} = 263^{\circ}\text{C/W}$	400°C/W



Power Dissipation



Measurement Board Pattern

○ IC Mount Area (Unit: mm)

Use in the oblique-line-area may have a bad influence on the long-term quality assurance. Recommendation duration time is up to 9,000 hours. 9,000 hours are corresponding to six years in case that this device is used for four hours a day.

POWER DISSIPATION (DFN (PLP)1612-4B)

This specification is determined under the condition of the device mounting on board. Power Dissipation (P_D) depends on conditions of mounting on board. This specification is based on the measurement at the conditions below:

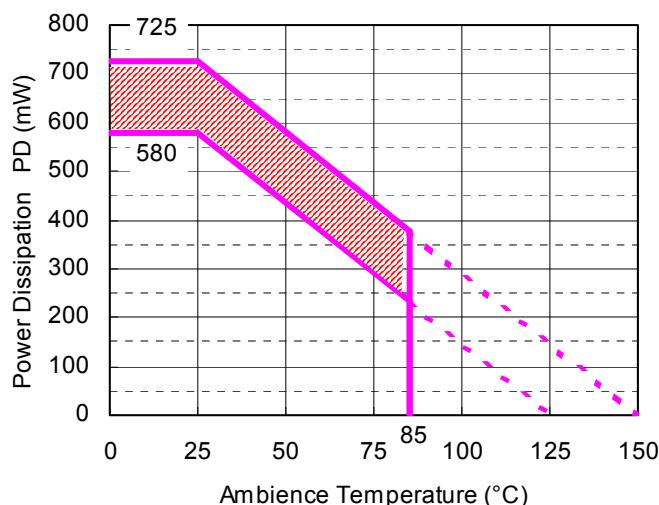
Measurement Conditions

	Standard Test Land Pattern
Environment	Mounting on Board (Wind velocity=0m/s)
Board Material	Glass cloth epoxy plastic (Double sided)
Board Dimensions	40mm*40mm*1.6mm
Copper Ratio	Top side: Approx. 50%, Back side: Approx. 50%
Through-holes	φ 0.54mm * 24pcs

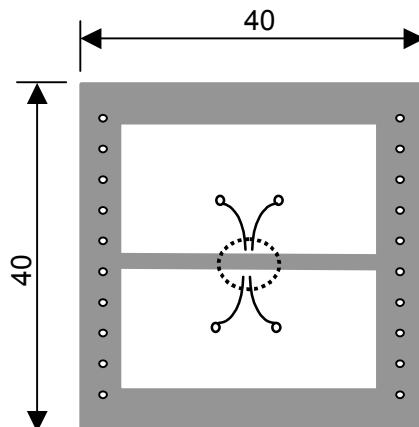
Measurement Result

(Ta=25°C)

	Standard Test Land Pattern
Power Dissipation	580mW (Tjmax=125°C) 725mW (Tjmax=150°C)
Thermal Resistance	$\theta_{ja} = (125-25\text{ }^{\circ}\text{C}) / 0.58\text{W} = 172\text{ }^{\circ}\text{C/W}$
	$\theta_{jc} = 51\text{ }^{\circ}\text{C/W}$



Power Dissipation



Measurent Board Pattern



IC Mount Area Unit: mm

* Use in the oblique-line-area may have a bad influence on the long-term quality assurance, Recommendation operating duration time is up to 13,000 hours. 13,000 hours are corresponding to nine years in case that this device is used for four hours a day.